



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

19-APR-2004

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #13436

TITLE: Qualification of FLIPCHIP INTERNATIONAL (FCI) for Bumped Products.

EFFECTIVE DATE: 19-Aug-2004

AFFECTED CHANGE CATEGORY:

Subcontractor Assembly Site
Assembly Process

AFFECTED PRODUCT DIVISION:

Mos Power Products
Discretes Products
Analog Products

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Won Kang <FFP6RB@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCEN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is an initial PCN announcing ON Semiconductor is qualifying FlipChip International (FCI) facility located in Phoenix, Arizona as an additional source for NUFxxx, NCPxxx, NLASxxx, devices. FCI is a fully certified ISO9002 and QS9000 supplier. There will be no change in the wafer/die source, therefore no electrical performance or specifications will change. This change is classified as a capacity expansion since the products listed below may be bumped at either FCI or the existing ASE qualified site once the final PCN expires.

**Initial Product/Process Change Notification #13436****QUALIFICATION PLAN:**

Qualification testing will be conducted on the following devices, representing the various technology groups within ON Semiconductor. Further reliability data will be gathered on new devices ON Semiconductor plans to release with the qualification of FCI. These new devices are also representative of the various technology groups within ON Semiconductor. Testing will consist of Temperature Cycling at -40C to 125C for 500 cycles with additional information at 1000 cycles. Additionally, High Temperature Operating Life will be conducted at device specific conditions, with a qualification point of 504 hours, and additional information at 1008 hours. Ball Shear data will be collected across a representative sampling.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):**PART**

NCP2890AFCT2
NLAS4684FCT1
NLAS4685FCT1
NUF4105FCT1
NUF6105FCT1
NUF6106FCT1